SOT-23 物 料 成 分 表

Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition	CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English		
Die	0.9	Si	7440-21-3	100.00%
Lead Frame	3.7	Cu	7440-50-8	balance
		Si	7440-21-3	0.25-1.2
		Mn	7439-96-5	0.1max
		Ni	7440-02-0	2.2-4.2
		Fe	7439-89-6	0.2max
		Zn	7440-66-6	1.0max
		Mg	7439-95-4	0.05-0.3
		Pb	7439-92-1	0.05max
		镀层Ag	7440-22-4	0.01-0.02max
Epoxy	0.073	Silver	7440-22-4	60-100%
		Epoxy Resin.	-	10-30%
		1,4-bis(2,3 epoxypropoxy)butane	2425-79-8	5-10%
		Aromatic polyamine Proprietary	-	1-5%
Wire	0.03	Copper	231-159-6	≥99.99
		Silver	231-131-3	<20ppm
		other	-	-
Mold Compound	4	Sillicon Dioxide	7631-86-9	60-80%
		Epoxy Cresol Novolac Resin~	29690-82-2	10-20%
		Phenol-formaldehyde polymer	9003-35-4	1- 10 %
		Mg-hydroxide	1309-42-8	1- 10 %
		3-Trimethoxysilylpropane-1-thiol	4420-74-0	0.1- 1 %
		Carbon black	1333-86-4	0.1- 1 %
Plating	0.03	Sn	7440-31-5	99.99%
Total	8.73			

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied.Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.